



FSD146MRBN Green-Mode Fairchild Power Switch (FPS™)

Features

- Advanced Soft Burst-Mode Operation for Low Standby Power and Low Audible Noise
- Random Frequency Fluctuation for Low EMI
- Pulse-by-Pulse Current Limit
- Various Protection Functions: Overload Protection (OLP), Over-Voltage Protection (OVP), Abnormal Over-Current Protection (AOCP), Internal Thermal Shutdown (TSD) with Hysteresis, Output-Short Protection (OSP), and Under-Voltage Lockout (UVLO) with Hysteresis
- Low Operating Current (0.4mA) in Burst Mode
- Internal Startup Circuit
- Internal High-Voltage SenseFET: 650V
- Built-in Soft-Start: 15ms
- Auto-Restart Mode

Description

The FSD146MRBN is an integrated Pulse Width Modulation (PWM) controller and SenseFET designed for offline Switch-Mode Power Supplies (SMPS) with minimal external components. The PWM controller includes an integrated fixed-frequency oscillator, Under-Voltage Lockout (UVLO), Leading-Edge Blanking (LEB), optimized gate driver, internal soft-start, temperature-compensated precise current sources for loop compensation, and self-protection circuitry. Compared with a discrete MOSFET and PWM controller solution, the FSD146MRBN can reduce total cost, component count, size, and weight; while simultaneously increasing efficiency, productivity, and system reliability. This device provides a basic platform that is well suited for cost-effective design of a flyback converter.

Applications

 Power Supply for LCD Monitor, STB, and DVD Combination

Ordering Information

					0	utput Pov	wer Table ⁽²⁾)						
Part	Package	Operating Junction Temperature	Limit					Currentikos		230V _{AC} ±	: 15% ⁽³⁾	85-265V _{AC}		Replaces
Number	r ackage			(Max.)	Adapter ⁽⁴⁾	Open Frame ⁽⁵⁾	Adapter ⁽⁴⁾	Open Frame ⁽⁵⁾	Device					
FSD146MRBN	8-DIP	−40°C ~ +125°C	1.50A	2.6Ω	23W	35W	17W	26W	FSFM260N					

Notes:

- 1. Lead-free package per JEDEC J-STD-020B.
- 2. The junction temperature can limit the maximum output power.
- 3. $230V_{AC}$ or $100/115V_{AC}$ with voltage doubler.
- 4. Typical continuous power in a non-ventilated enclosed adapter measured at 50°C ambient temperature.
- 5. Maximum practical continuous power in an open-frame design at 50°C ambient temperature.

Application Circuit

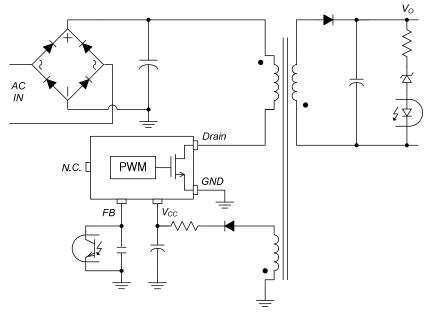


Figure 1. Typical Application Circuit

Internal Block Diagram

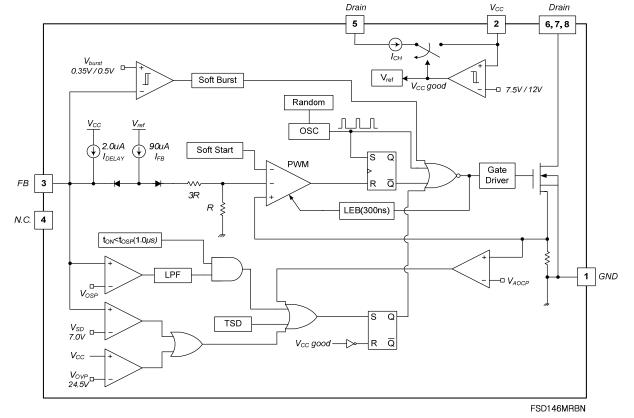


Figure 2. Internal Block Diagram

Pin Configuration

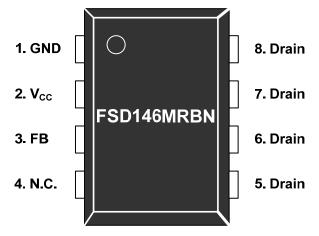


Figure 3. Pin Configuration (Top View)

Pin Definitions

Pin#	Name	Description
1	GND	Ground. This pin is the control ground and the SenseFET source.
2	V _{CC}	Power Supply . This pin is the positive supply input, which provides the internal operating current for both startup and steady-state operation.
3	FB	Feedback . This pin is internally connected to the inverting input of the PWM comparator. The collector of an opto-coupler is typically tied to this pin. For stable operation, a capacitor should be placed between this pin and GND. If the voltage of this pin reaches 7.0V, the overload protection triggers, which shuts down the FPS™.
4	N.C.	No Connection
5, 6, 7, 8	Drain	SenseFET Drain. High-voltage power SenseFET drain connection.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol		Parameter			Max.	Unit
V _{DS}	Drain Pin Voltage				650	V
V _{CC}	V _{CC} Pin Voltage				26	V
V_{FB}	Feedback Pin Voltage			-0.3	10.0	V
I _{DM}	Drain Current Pulsed				3.4	А
	(6)		T _C =25°C		1.7	А
I _{DS}	Continuous Switching	Drain Current	T _C =100°C		1.1	А
E _{AS}	Single Pulsed Avalance	Single Pulsed Avalanche Energy ⁽⁷⁾				mJ
P _D	Total Power Dissipation	on (T _C =25°C) ⁽⁸⁾			1.5	W
_	Maximum Junction Te	Maximum Junction Temperature				°C
TJ	Operating Junction Te		-40	+125	°C	
T _{STG}	Storage Temperature	-55	+150	°C		
ECD	Electrostatic	Human Body Mode	uman Body Model, JESD22-A114		5	147
ESD	Discharge Capability	Charged Device M	ed Device Model, JESD22-C101		2	kV

Notes:

- 6. Repetitive peak switching current when the inductive load is assumed: Limited by maximum duty (D_{MAX}=0.73) and junction temperature (see Figure 4).
- 7. L=45mH, starting T_J=25°C.
- 8. Infinite cooling condition (refer to the SEMI G30-88).
- 9. Although this parameter guarantees IC operation, it does not guarantee all electrical characteristics.

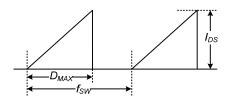


Figure 4. Repetitive Peak Switching Current

Thermal Impedance

T_A=25°C unless otherwise specified.

Symbol	Parameter	Value	Unit
θ_{JA}	Junction-to-Ambient Thermal Impedance ⁽¹⁰⁾	85	°C/W
Ψ_{JL}	Junction-to-Lead Thermal Impedance ⁽¹¹⁾	11	°C/W

Notes:

- 10. JEDEC recommended environment, JESD51-2, and test board, JESD51-10, with minimum land pattern.
- 11. Measured on the SOURCE pin #7, close to the plastic interface.

Electrical Characteristics

 $T_J = 25^{\circ}C$ unless otherwise specified.

Symbol	Parameter		Conditions	Min.	Тур.	Max.	Unit
SenseFET	Section		,				
BV _{DSS}	Drain-Source B	reakdown Voltage	$V_{CC} = 0V, I_D = 250\mu A$	650			V
I _{DSS}	Zero-Gate-Volta	age Drain Current	V _{DS} = 650V, T _A = 25°C			250	μΑ
R _{DS(ON)}	Drain-Source O	n-State Resistance	V _{GS} =10V, I _D =1A		2.1	2.6	Ω
C _{ISS}	Input Capacitan	ice ⁽¹²⁾	V _{DS} = 25V, V _{GS} = 0V, f=1MHz		436		pF
Coss	Output Capacita		V_{DS} = 25V, V_{GS} = 0V, f=1MHz		65		pF
t _r	Rise Time		$V_{DS} = 325V$, $I_D = 4A$, $R_G = 25\Omega$		24		ns
t _f	Fall Time		$V_{DS} = 325V$, $I_D = 4A$, $R_G = 25\Omega$		24		ns
t _{d(on)}	Turn-On Delay		$V_{DS} = 325V$, $I_D = 4A$, $R_G = 25\Omega$		13		ns
$t_{\text{d(off)}}$	Turn-Off Delay		V_{DS} = 325V, I_{D} = 4A, R_{G} =25 Ω		30		ns
Control Se	ction						
f _S	Switching Frequ	uency ⁽¹²⁾	V _{CC} = 14V, V _{FB} = 4V	61	67	73	kHz
Δf_{S}	Switching Frequ	uency Variation ⁽¹²⁾	-25°C < T _J < 125°C		±5	±10	%
D_MAX	Maximum Duty	Ratio	V _{CC} = 14V, V _{FB} = 4V	61	67	73	%
D _{MIN}	Minimum Duty F	Ratio	V _{CC} = 14V, V _{FB} = 0V			0	%
I _{FB}	Feedback Source Current		V _{FB} = 0	65	90	115	μΑ
V _{START}	UVLO Threshold Voltage		V _{FB} = 0V, V _{CC} Sweep	11	12	13	V
V _{STOP}			After Turn-On, V _{FB} = 0V	7.0	7.5	8.0	V
t _{S/S}	Internal Soft-Sta	art Time	V _{STR} = 40V, V _{CC} Sweep		15		ms
V_{RECOMM}	Recommended	V _{CC} Range		13		23	V
Burst-Mode	e Section						
V_{BURH}				0.45	0.50	0.55	V
V_{BURL}	Burst-Mode Vol	tage	V _{CC} = 14V, V _{FB} Sweep	0.30	0.35	0.40	V
V _{HYS}					150		mV
Protection	Section						
I _{LIM}	Peak Drain Cur	rent Limit	di/dt = 300mA/μs	1.35	1.50	1.65	Α
V _{SD}	Shutdown Feed	lback Voltage	V _{CC} = 14V, V _{FB} Sweep	6.45	7.00	7.55	V
I _{DELAY}	Shutdown Delay	y Current	V _{CC} = 14V, V _{FB} = 4V	1.2	2.0	2.8	μΑ
t _{LEB}	Leading-Edge E	Blanking Time(12,14)			300		ns
V_{OVP}	Over-Voltage P		V _{CC} Sweep	23.0	24.5	26.0	V
t _{OSP}		Threshold Time	OSP Triggered when	0.7	1.0	1.3	μS
V _{OSP}	Output-Short Protection ⁽¹²⁾	Threshold V _{FB}	ton <tosp &="" vfb="">VOSP</tosp>	1.8	2.0	2.2	V
t _{OSP_FB}	1.1010011011	V _{FB} Blanking Time	(Lasts Longer than t _{OSP_FB})	2.0	2.5	3.0	μS
TSD	Th	T (12)	Shutdown Temperature	125	135	145	°C
	Thermal Shutdown Temperature ⁽¹²⁾				 		

Continued on the following page...

Electrical Characteristics (Continued)

 T_J = 25°C unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
Total Devic	Total Device Section						
I _{OP}	Operating Supply Current, (Control Part in Burst Mode)	V _{CC} = 14V, V _{FB} = 0V	0.3	0.4	0.5	mA	
I _{OPS}	Operating Switching Current, (Control Part and SenseFET Part)	V _{CC} = 14V, V _{FB} = 2V	1.1	1.5	1.9	mA	
I _{START}	Start Current	V _{CC} =11V (Before V _{CC} Reaches V _{START})	85	120	155	μΑ	
I _{CH}	Startup Charging Current	$V_{CC} = V_{FB} = 0V$, $V_{STR} = 40V$	0.7	1.0	1.3	mA	
V _{STR}	Minimum V _{STR} Supply Voltage	$V_{CC} = V_{FB} = 0V, V_{STR}$ Sweep		26		V	

Notes:

- 12. Although these parameters are guaranteed, they are not 100% tested in production.
- 13. Average value.
- 14. t_{LEB} includes gate turn-on time.

Comparison of FSGM300N and FSD146MRBN

Function	FSGM300N	FSD146MRBN	Advantages of FSD146MRBN
Operating Current	1.5mA	0.4mA	Very low standby power
Power Balance	Long t _{CLD}	Very Short T _{CLD}	The difference of input power between the low and high input voltage is quite small.

Typical Performance Characteristics

Characteristic graphs are normalized at T_A=25°C.

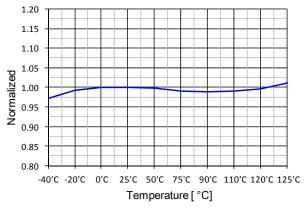


Figure 5. Operating Supply Current (IOP) vs. TA

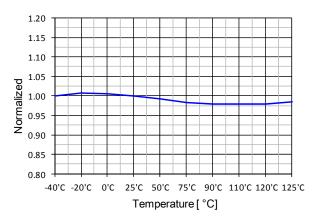


Figure 6. Operating Switching Current (I_{OPS}) vs. T_A

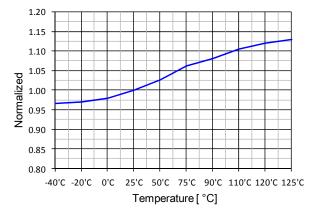


Figure 7. Startup Charging Current (I_{CH}) vs. T_A

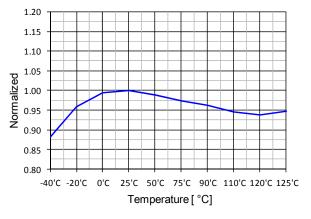


Figure 8. Peak Drain Current Limit (ILIM) vs. TA

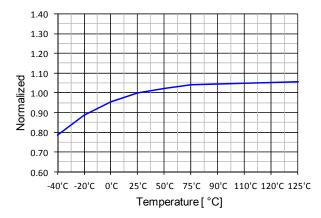


Figure 9. Feedback Source Current (IFB) vs. TA

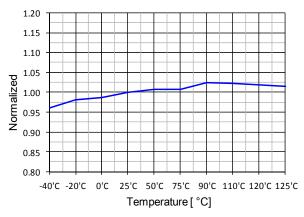
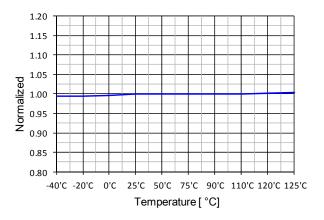


Figure 10. Shutdown Delay Current (IDELAY) vs. TA

Typical Performance Characteristics

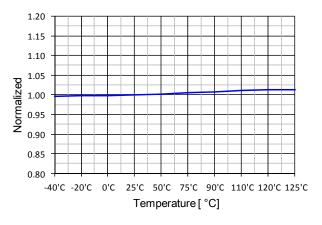
Characteristic graphs are normalized at T_A=25°C.



1.20
1.15
1.10
1.05
1.00
0.95
0.90
0.85
0.80
-40'C -20'C 0'C 25'C 50'C 75'C 90'C 110'C 120'C 125'C
Temperature [°C]

Figure 11. UVLO Threshold Voltage (V_{START}) vs. T_A

Figure 12. UVLO Threshold Voltage (VSTOP) vs. TA



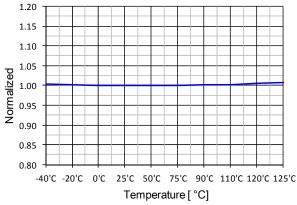
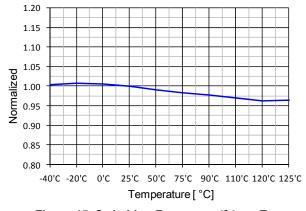


Figure 13. Shutdown Feedback Voltage (V_{SD}) vs. T_A

Figure 14. Over-Voltage Protection (V_{OVP}) vs. T_{A}



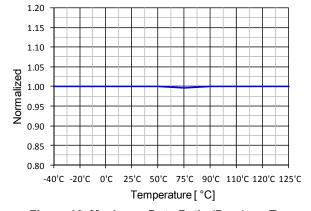


Figure 15. Switching Frequency (fs) vs. TA

Figure 16. Maximum Duty Ratio (D_{MAX}) vs. T_A

Functional Description

1. Startup: At startup, an internal high-voltage current source supplies the internal bias and charges the external capacitor (C_{Vcc}) connected to the V_{CC} pin, as illustrated in Figure 17. When V_{CC} reaches 12V, the FSD146MRBN begins switching and the internal high-voltage current source is disabled. The FSD146MRBN continues normal switching operation and the power is supplied from the auxiliary transformer winding unless V_{CC} goes below the stop voltage of 7.5V.

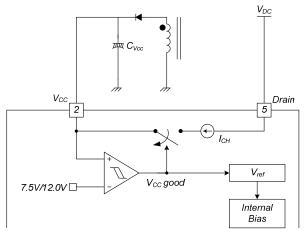


Figure 17. Startup Block

2. Soft-Start: The FSD146MRBN has an internal soft-start circuit that increases PWM comparator inverting input voltage, together with the SenseFET current, slowly after it starts. The typical soft-start time is 15ms. The pulse width to the power switching device is progressively increased to establish the correct working conditions for transformers, inductors, and capacitors. The voltage on the output capacitors is progressively increased to smoothly establish the required output voltage. This helps prevent transformer saturation and reduces stress on the secondary diode during startup.

- **3. Feedback Control**: This device employs current-mode control, as shown in Figure 18. An opto-coupler (such as the FOD817) and shunt regulator (such as the KA431) are typically used to implement the feedback network. Comparing the feedback voltage with the voltage across the R_{SENSE} resistor makes it possible to control the switching duty cycle. When the reference pin voltage of the shunt regulator exceeds the internal reference voltage of 2.5V, the opto-coupler LED current increases, pulling down the feedback voltage and reducing drain current. This typically occurs when the input voltage is increased or the output load is decreased.
 - 3.1 Pulse-by-Pulse Current Limit: Because current-mode control is employed, the peak current through the SenseFET is limited by the inverting input of the PWM comparator (V_{FB}^*), as shown in Figure 18. Assuming that the 90 μ A current source flows only through the internal resistor (3R + R =27k Ω), the cathode voltage of diode D2 is about 2.5V. Since D1 is blocked when the feedback voltage (V_{FB}) exceeds 2.5V, the maximum voltage of the cathode of D2 is clamped at this voltage. Therefore, the peak value of the current through the SenseFET is limited.
 - **3.2 Leading-Edge Blanking (LEB)**: At the instant the internal SenseFET is turned on, a high-current spike usually occurs through the SenseFET, caused by primary-side capacitance and secondary-side rectifier reverse recovery. Excessive voltage across the R_{SENSE} resistor leads to incorrect feedback operation in the current-mode PWM control. To counter this effect, the FSD146MRBN employs a leading-edge blanking (LEB) circuit. This circuit inhibits the PWM comparator for t_{LEB} (300ns) after the SenseFET is turned on.

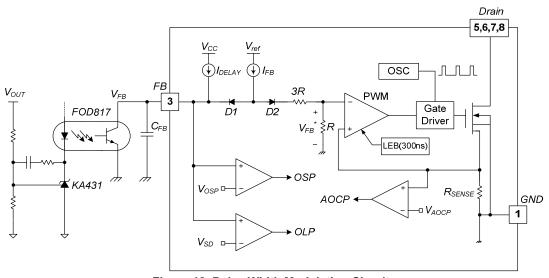


Figure 18. Pulse Width Modulation Circuit

4. Protection Circuits: The FSD146MRBN has several self-protective functions, such as Overload Protection (OLP), Abnormal Over-Current Protection (AOCP), Output-Short Protection (OSP), Over-Voltage Protection (OVP), and Thermal Shutdown (TSD). All the protections are implemented as auto-restart. Once the fault condition is detected, switching is terminated and the SenseFET remains off. This causes V_{CC} to fall. When V_{CC} falls to the Under-Voltage Lockout (UVLO) stop voltage of 7.5V, the protection is reset and the startup circuit charges the V_{CC} capacitor. When V_{CC} reaches the start voltage of 12.0V, the FSD146MRBN resumes normal operation. If the fault condition is not removed, the SenseFET remains off and V_{CC} drops to stop voltage again. In this manner, the auto-restart can alternately enable and disable the switching of the power SenseFET until the fault condition is eliminated. Because these protection circuits are fully integrated into the IC without external components, the reliability is improved without increasing cost.

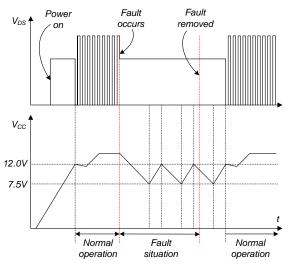


Figure 19. Auto-Restart Protection Waveforms

4.1 Overload Protection (OLP): Overload is defined as the load current exceeding its normal level due to an unexpected abnormal event. In this situation, the protection circuit should trigger to protect the SMPS. However, in normal operation, the overload protection circuit can be triggered during the load transition. To avoid this undesired operation, the overload protection circuit is designed to trigger only after a specified time to determine whether it is a transient situation or a true overload situation. Because of the pulse-by-pulse current limit capability, the maximum peak current through the SenseFET is limited and, therefore, the maximum input power is restricted with a given input voltage. If the output consumes more than this maximum power, the output voltage (Vout) decreases below the set voltage. This reduces the current through the opto-coupler LED, which also reduces the opto-coupler transistor current, thus increasing the feedback voltage (V_{FB}). If V_{FB} exceeds 2.5V, D1 is blocked and the 2.0µA current source starts to charge C_{FB} slowly up. In this condition, V_{FB} continues increasing until it reaches 7.0V, when the switching operation is terminated, as shown in Figure 20. The delay for shutdown is the time required to charge C_{FB} from 2.5V to 7.0V with 2.0µA. A 25 \sim 50ms delay is typical for most applications. This protection is implemented in auto-restart mode.

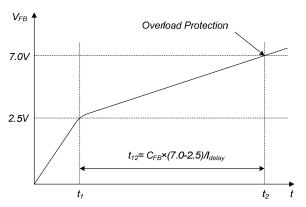


Figure 20. Overload Protection

4.2 Abnormal Over-Current Protection (AOCP): When the secondary rectifier diodes or the transformer pins are shorted, a steep current with extremely high di/dt can flow through the SenseFET during the minimum turn-on time. Even though the FSD146MRBN has overload protection, it is not enough to protect the FSD146MRBN in that abnormal case; since severe current stress is imposed on the SenseFET until OLP is triggered. The FSD146MRBN internal AOCP circuit is shown in Figure 21. When the gate turn-on signal is applied to the power SenseFET, the AOCP block is enabled and monitors the current through the sensing resistor. The voltage across the resistor is compared with a preset AOCP level. If the sensing resistor voltage is greater than the AOCP level, the set signal is applied to the S-R latch, resulting in the shutdown of the SMPS.

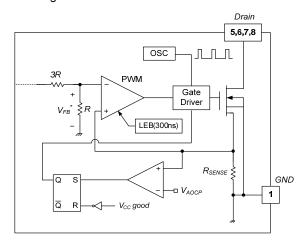


Figure 21. Abnormal Over-Current Protection

4.3. Output-Short Protection (OSP): If the output is shorted, steep current with extremely high di/dt can flow through the SenseFET during the minimum turnon time. Such a steep current brings high-voltage stress on the drain of the SenseFET when turned off. OSP protects the device from this abnormal condition. It is comprised of detecting V_{FB} and SenseFET turnon time. When the V_{FB} is higher than 2.0V and the SenseFET turn-on time is lower than 1.0 μ s, this condition is recognized as an abnormal error and PWM switching shuts down until V_{CC} reaches V_{START} again. An abnormal condition output short is shown in Figure 22.

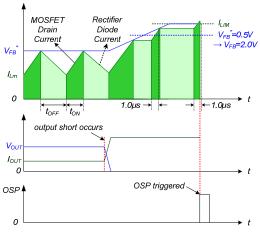


Figure 22. Output-Short Protection

- Over-Voltage Protection (OVP): If the secondary-side feedback circuit malfunctions or a solder defect causes an opening in the feedback path, the current through the opto-coupler transistor becomes almost zero. Then VFB climbs up in a similar manner to the overload situation, forcing the preset maximum current to be supplied to the SMPS until the overload protection is triggered. Because more energy than required is provided to the output, the output voltage may exceed the rated voltage before the overload protection is triggered, resulting in the breakdown of the devices in the secondary side. To prevent this situation, an OVP circuit is employed. In general, the V_{CC} is proportional to the output voltage and the FSD146MRBN uses V_{CC} instead of directly monitoring the output voltage. If V_{CC} exceeds 24.5V, an OVP circuit is triggered, resulting in the termination of the switching operation. To avoid undesired activation of OVP during normal operation, V_{CC} should be designed to be below 24.5V.
- **4.5 Thermal Shutdown (TSD)**: The SenseFET and the control IC on a die in one package make it easier for the control IC to detect the over temperature of the SenseFET. If the temperature exceeds ~135°C, the thermal shutdown is triggered and stops operation. The FSD146MRBN operates in auto-restart mode until the temperature decreases to around 75°C, when normal operation resumes.

5. Soft Burst-Mode Operation: To minimize power dissipation in Standby Mode, the FSD146MRBN enters Burst-Mode operation. As the load decreases, the feedback voltage decreases. As shown in Figure 23, the device automatically enters Burst Mode when the feedback voltage drops below V_{BURL} (350mV). At this point, switching stops and the output voltages start to drop at a rate dependent on the standby current load. This causes the feedback voltage to rise. Once it passes V_{BURH} (500mV), switching resumes. The feedback voltage then falls and the process repeats. Burst Mode alternately enables and disables switching of the SenseFET, thereby reducing switching loss in Standby Mode.

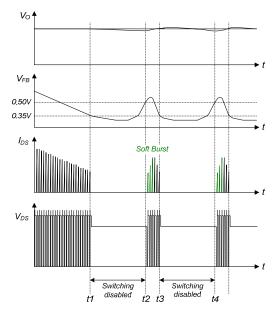


Figure 23. Burst Mode Operation

6. Random Frequency Fluctuation (RFF): Fluctuating switching frequency of an SMPS can reduce EMI by spreading the energy over a wide frequency range. The amount of EMI reduction is directly related to the switching frequency variation, which is limited internally. The switching frequency is determined randomly by external feedback voltage and internal free-running oscillator at every switching instant. RFF effectively scatters the EMI noise around typical switching frequency (67kHz) and can reduce the cost of the input filter used to meet EMI requirements (e.g. EN55022).

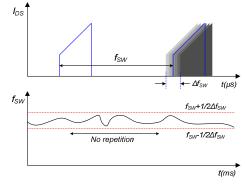


Figure 24. Random Frequency Fluctuation

Typical Application Circuit

Application	Input Voltage	Rated Output	Rated Power
LCD Monitor Power Supply	85 ~ 265V _{AC}	5.0V(2A) 14.0V(1.2A)	26.8W

Key Design Notes:

- 1. The delay for overload protection is designed to be about 30ms with C105 (8.2nF). OLP time between 39ms (12nF) and 46ms (15nF) is recommended.
- 2. The SMD-type capacitor (C106) must be placed as close as possible to the V_{CC} pin to avoid malfunction by abrupt pulsating noises and to improve ESD and surge immunity. Capacitance between 100nF and 220nF is recommended.

Schematic

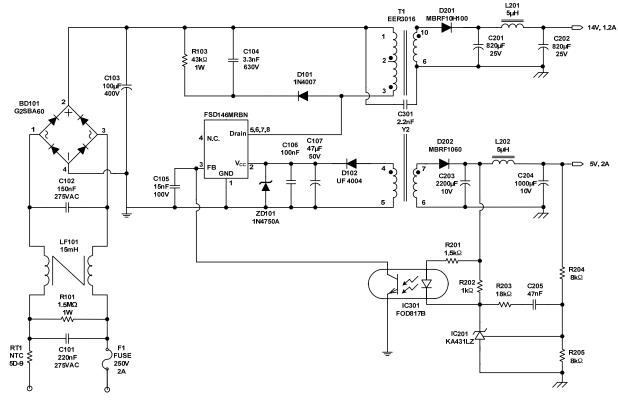


Figure 25. Schematic

Transformer

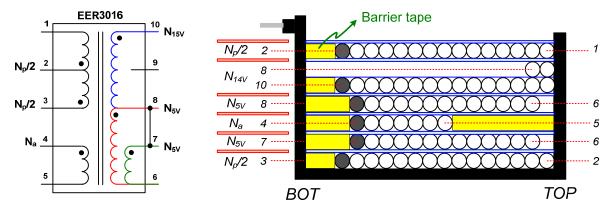


Figure 26. Schematic of Transformer

Winding Specification

	Dim/S E)	Wino	Turno	Winding Mathod	Ва	arrier Tape	9
	Pin(S → F)	Wire	Turns	Winding Method	ТОР	вот	Ts
N _p /2	3 → 2	0.25φ×1	22	Solenoid Winding		2.0mm	1
Insulation: Polyest	er Tape t = 0.025n	nm, 2 Layers					
N _{5V}	7 → 6	0.4φ×2 (TIW)	3	Solenoid Winding		3.0mm	1
Insulation: Polyest	er Tape t = 0.025n	nm, 2 Layers					
Na	4 → 5	0.2φ×1	8	Solenoid Winding	4.0mm	3.0mm	1
Insulation: Polyest	er Tape t = 0.025n	nm, 2 Layers					
N _{5V}	8 → 6	0.4φ×2 (TIW)	3	Solenoid Winding		3.0mm	1
Insulation: Polyester Tape t = 0.025mm, 2 Layers							
N _{14V}	10 → 8	0.4φ×2 (TIW)	5	Solenoid Winding		2.0mm	1
Insulation: Polyester Tape t = 0.025mm, 2 Layers							
N _p /2	2 → 1	0.25φ×1	22	Solenoid Winding		2.0mm	1
Insulation: Polyester Tape t = 0.025mm, 2 Layers							

Electrical Characteristics

	Pin		Remark	
Inductance	1-3	826μH ±6%	67kHz, 1V	
Leakage	1-3	15μH Maximum	Short all other pins	

Core & Bobbin

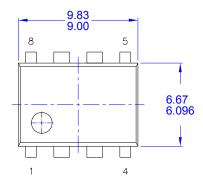
Core: EER3016 (Ae=109.7mm²)

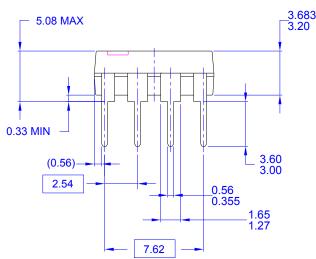
■ Bobbin: EER3016

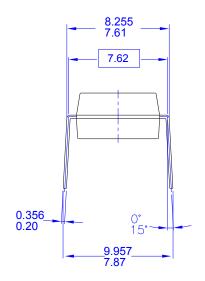
Bill of Materials

Part #	Value	Note	Part #	Value	Note	
	Fuse		Capacitor			
F101	250V 2A		C101	220nF/275V	Box (Pilkor)	
	NTC		C102	150nF/275V	Box (Pilkor)	
NTC101	5D-9	DSC	C103	100μF/400V	Electrolytic (SamYoung)	
	Resistor		C104	3.3nF/630V	Film (Sehwa)	
R101	1.5MΩ, J	1W	C105	15nF/100V	Film (Sehwa)	
R103	43kΩ, J	1W	C106	100nF	SMD (2012)	
R201	1.5kΩ, F	1/4W, 1%	C107	47μF/50V	Electrolytic (SamYoung)	
R202	1.0kΩ, F	1/4W, 1%	C201	820μF/25V	Electrolytic (SamYoung)	
R203	18kΩ, F	1/4W, 1%	C202	820μF/25V	Electrolytic (SamYoung)	
R204	8kΩ, F	1/4W, 1%	C203	2200μF/10V	Electrolytic (SamYoung)	
R205	8kΩ, F	1/4W, 1%	C204	1000μF/16V	Electrolytic (SamYoung)	
			C205	47nF/100V	Film (Sehwa)	
			C301	2.2nF/Y2	Y-cap (Samhwa)	
	IC		Inductor			
FPS	FSD146MRBN	Fairchild	LF101	20mH	Line filter 0.5Ø	
IC201	KA431LZ	Fairchild	L201	5μΗ	5A Rating	
IC301	FOD817B	Fairchild	L202	5μΗ	5A Rating	
	Diode		Transformer			
D101	1N4007	Vishay	T101	826µH		
D102	UF4007	Vishay				
ZD101	1N4750	Vishay				
D201	MBRF10H100	Fairchild				
D202	MBRF1060	Fairchild				
BD101	G2SBA60	Vishay				

Physical Dimensions







NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MS-001 VARIATION BA
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D) DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994
- E) DRAWING FILENAME AND REVSION: MKT-N08FREV2.

Figure 27. 8-Lead, MDIP, JEDEC MS-001, .300" Wide

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Definition of Terms

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